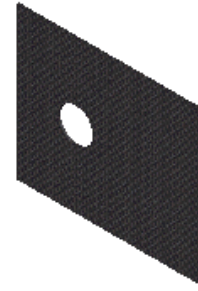


Product- information Type: SI488

Group: Insulating and mounting accessories

Silicone wafers, glass fiber reinforced

Areas of application (Cases):	TO220
Thickness:	0.18 mm
Material:	Silicone foil
Thermal resistance	1.3 K/W
Temperature rating:	200 °C
Dielectric strength:	4 KV



Silicone foil (glass fiber reinforced) in combination with insulating bushes facilitate insulated mounting of semiconductors e.g. on heatsinks.

They are highly flexible and ensure optimal heat conductivity even without using thermal compounds.

- Dielectric strength: (Test ASTM D 149) ca. 4 KV
- Dielectric constant: (Test ASTM D 150) 2,56 (by 106 Hz)
- Hardness: (Test ASTM D 2240) 85 Shore A
- Elongation: (Test ASTM D 412) 2%

Thermal resistance Rth (K/W) without thermal compound.

UL listed

